## Surface Mount Schottky Power Rectifier

The MBRS540T3 employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system.

### Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guard-Ring for Stress Protection
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are PB-Free Packages\*

### **Mechanical Characteristics**

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 217 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Notch in Plastic Body Indicates Cathode Lead
- ESD Rating:
  - ♦ Machine Model, C (> 400 V)

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- Human Body Model, 3B (> 8000 V)
- Device Meets MSL 1 Requirements



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### SCHOTTKY BARRIER RECTIFIER 5.0 AMPERES, 40 VOLTS



SMC CASE 403 PLASTIC

### MARKING DIAGRAM



B540	= Specific Device Code
А	= Assembly Location
Y	= Year
WW	= Work Week
•	= Pb-Free Package

(Note: Microdot may be in either location)

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MBRS540T3G	SMC (Pb-Free)	2,500 / Tape & Reel
NRVBS540T3G	SMC (Pb-Free)	2,500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

BDTIC.com/

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
Average Rectified Forward Current (At Rated V <sub>R</sub> , T <sub>C</sub> = 105°C)	I <sub>F(AV)</sub>	5	A
Peak Repetitive Forward Current (At Rated $V_R$ , Square Wave, 20 KHz, $T_C = 80^{\circ}C$ )	I <sub>FRM</sub>	10	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	190	A
Storage Temperature Range	Tstg	-65 to +150	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +150	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10,000	V/µs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

### **THERMAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Thermal Resistance,			°C/W
Junction-to-Lead (Note 2)	$R_{\theta JL}$	12	
Thermal Resistance,			
Junction-to-Ambient (Note 2)	$R_{ extsf{ heta}JA}$	111	

2. Rating applies when surface mounted on the minimum pad size recommended.

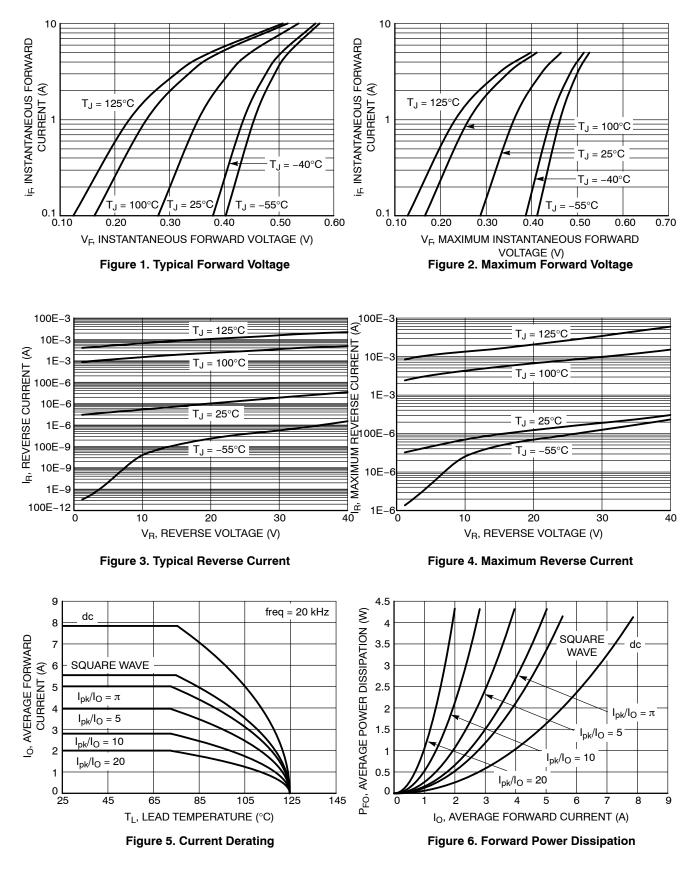
### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) (i <sub>F</sub> = 5.0 A, T <sub>C</sub> = 25°C)	V <sub>F</sub>	0.50	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, T <sub>C</sub> = 25°C) (Rated dc Voltage, T <sub>C</sub> = 100°C)	İR	0.3 15	mA

3. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

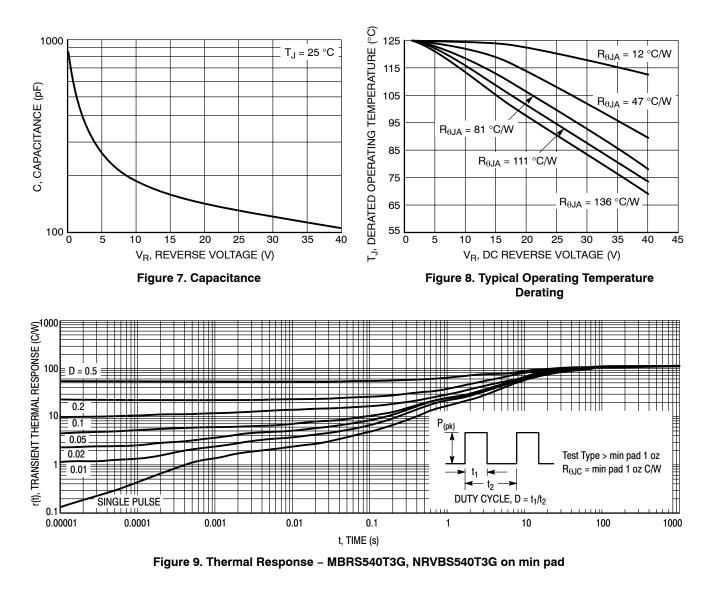
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### **TYPICAL CHARACTERISTICS**



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### **TYPICAL CHARACTERISTICS**



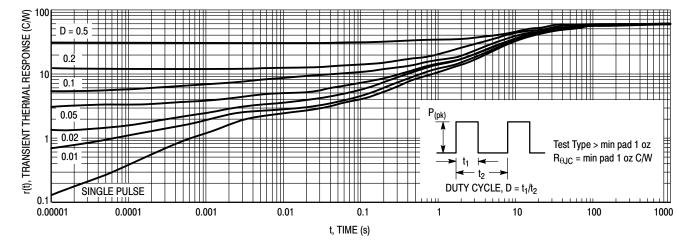
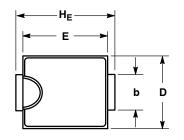


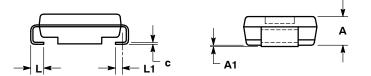
Figure 10. Thermal Response - MBRS540T3G, NRVBS540T3G on 1" pad

www.BD<sup>htp://nsemil.com</sup>com/ON/

### PACKAGE DIMENSIONS

SMC CASE 403–03 ISSUE E





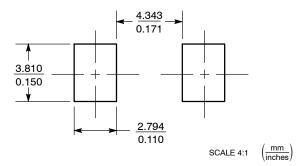
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: INCH.
- 3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

4.	403-01	THRU	-02 OBS	OLETE,	NEW	STANDA	٩RD	403-03
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	м	ILLIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.90	2.13	2.41	0.075	0.084	0.095	
A1	0.05	0.10	0.15	0.002	0.004	0.006	
b	2.92	3.00	3.07	0.115	0.118	0.121	
С	0.15	0.23	0.30	0.006	0.009	0.012	
D	5.59	5.84	6.10	0.220	0.230	0.240	
Е	6.60	6.86	7.11	0.260	0.270	0.280	
HE	7.75	7.94	8.13	0.305	0.313	0.320	
L	0.76	1.02	1.27	0.030	0.040	0.050	
L1	0.51 REF			0.020 REF			

SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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MBRS540T3/D